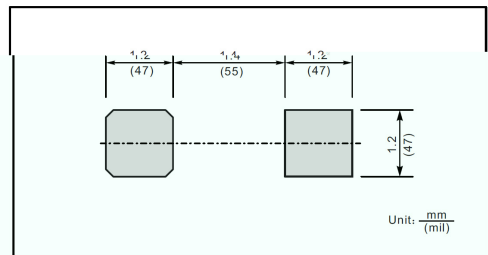


The recommended mounting pad size





	θ		



Fig.1 Power Derating Curve

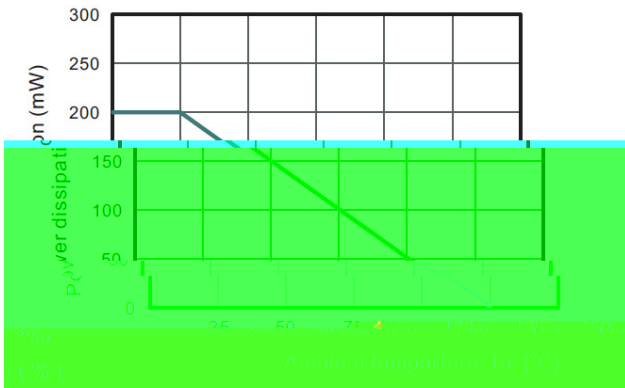
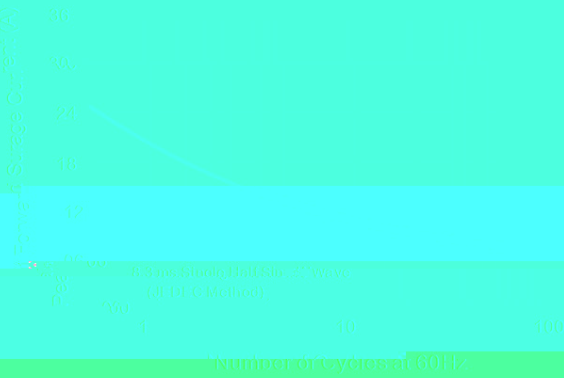
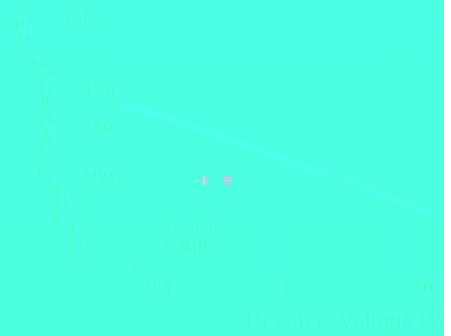
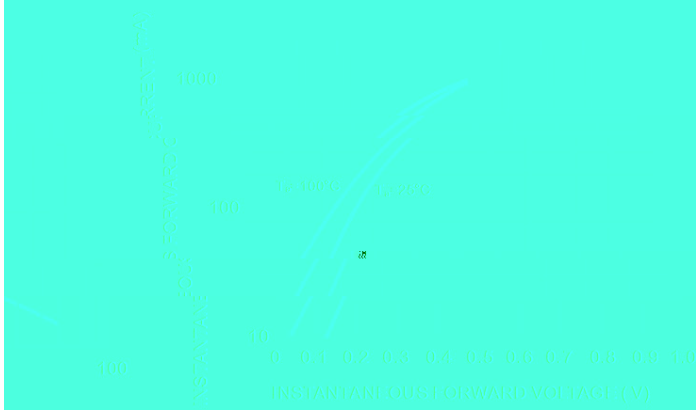
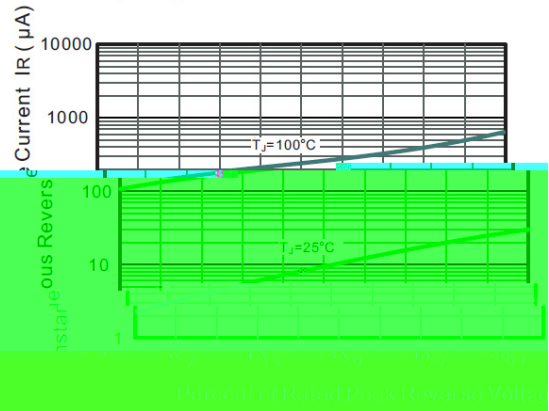
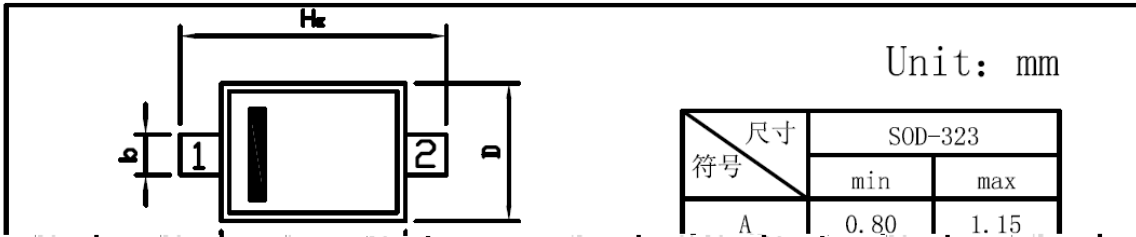
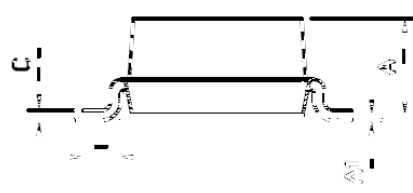


Fig.2 Typical Reverse Characteristics



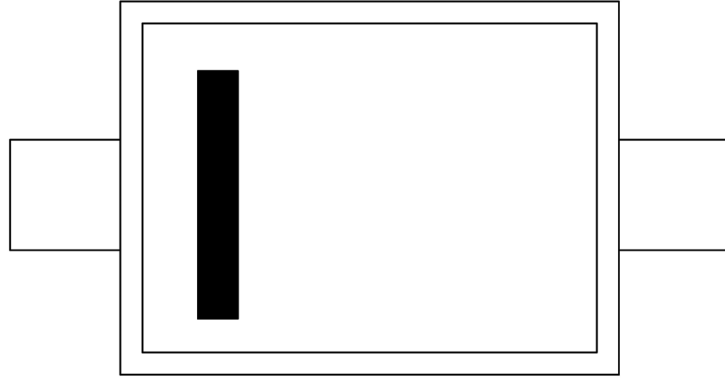


A	0.80	1.15
b	0.25	0.40
C	0.08	0.18
D	1.20	1.40
E	1.40	1.80
E	2.50	2.80
L	0.20	0.45

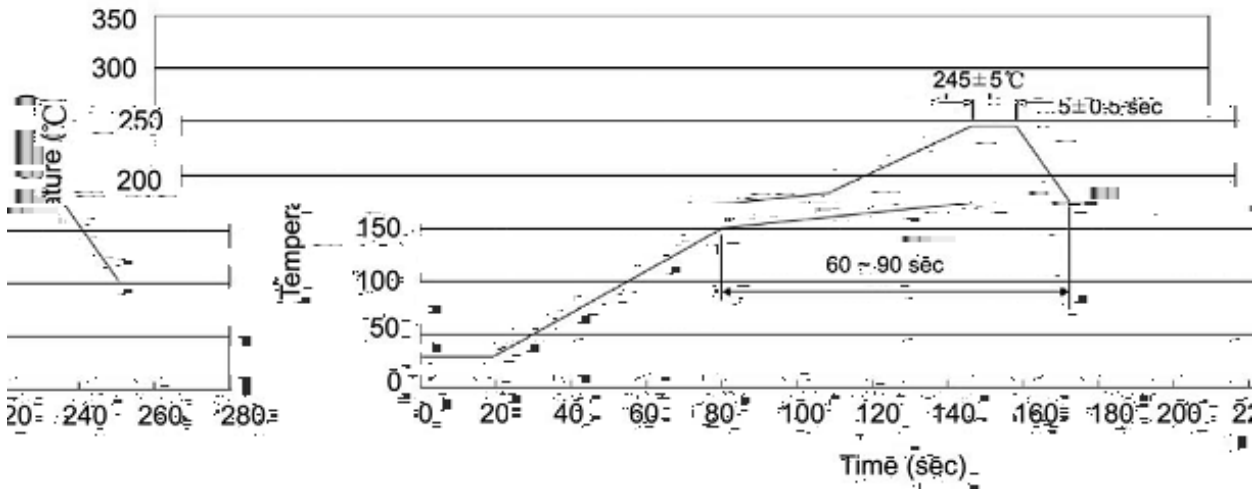


PIN: 1.CAT J 2.AN J

S J-323



Temperature Profile for IR Reflow Soldering (Pb-Free)



封装形式	包装数量					包装尺寸		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-323	3,000	10	30,000	6	180,000	7 × 8	180×120×180	390×385×205